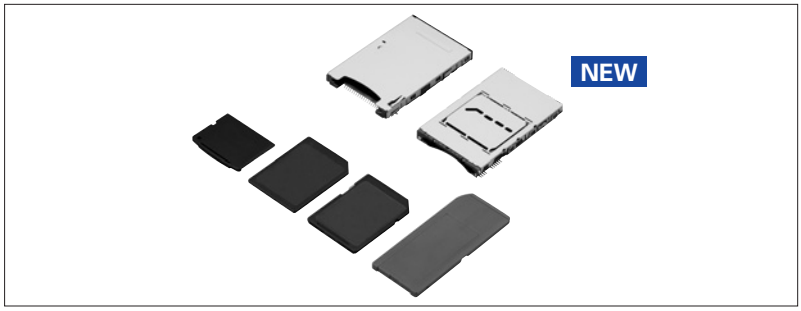
Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™, xD-Picture Card™)

SCDE Series

RoHS applicable

Push-in push-out eject mechanism applicable to four media types.



Features

- Applicable to four memory card standards - SD Memory Card, Multi Media Card™, Memory Stick™ and xD-Picture Card™.
- Push-push ejection mechanism applied in both card types.
- Same insertion and ejection position applied for both cards.

Applications

- For desktop PCs, notebook PCs, various personal digital assistants, digital still cameras, digital camcorders, facsimile machines and printers.
- For home audio equipment (TVs and set top boxes)
- For audio systems
- For portable memory players

Typical Specifications

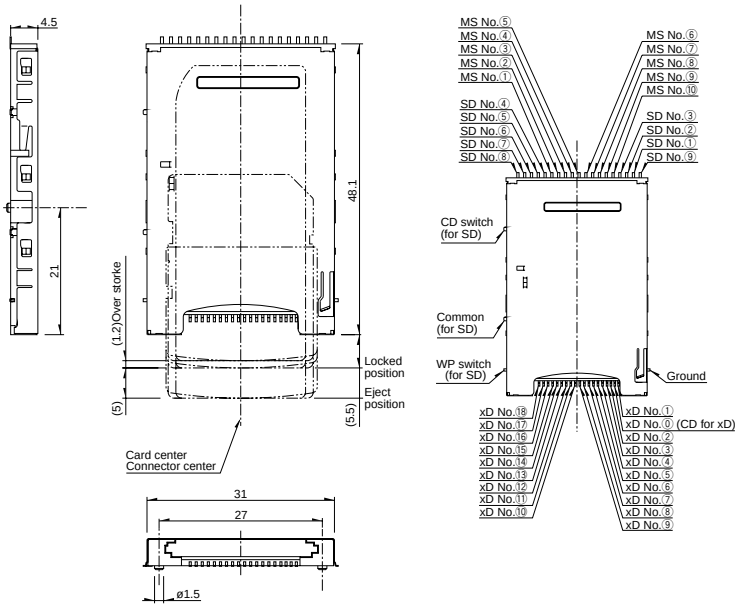
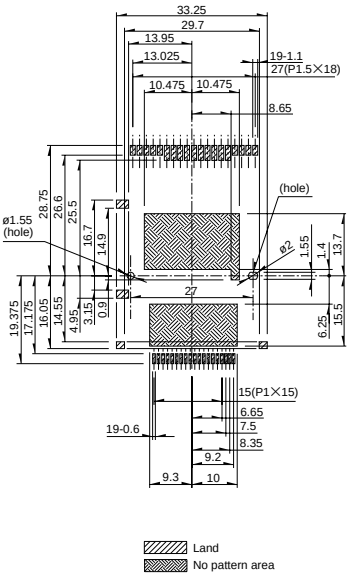
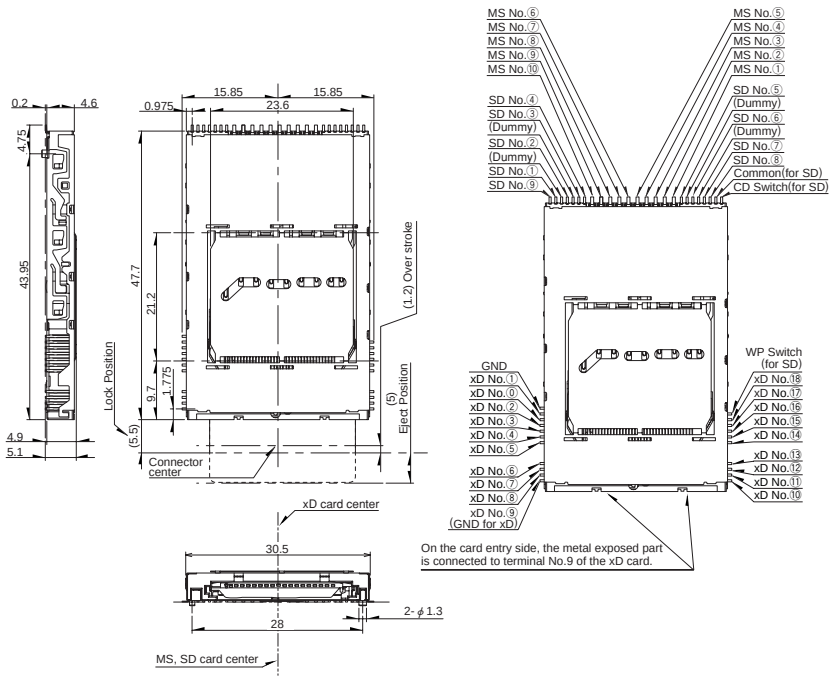
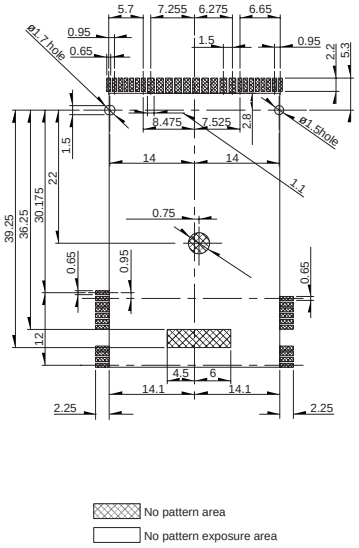
Items			Specifications
Structure	Applicable media		SD Memory Card
			MultiMediaCard™
			Memory Stick™
			xD-Picture Card™
	Mounting type		Surface mounting type
	Mounting style		Standard mount / Reverse mount
	Media ejection structure		Push-push type
Performance	Operating temperature range		−10℃ to +60℃
	Voltage proof		500V AC 1minute (SCDE1), 250V AC 1minute (SCDE2)
	Insulation resistance (Initial)		1,000MΩ min.
	Contact resistance (Initial)	Connector contacts	100mΩ max. (SCDE1), 150mΩ max. (SCDE2)
		Detection switch	500mΩ max. (SCDE1), 600mΩ max. (SCDE2)
	Insertion and removal cycle		10,000cycles (SD Memory Card, xD-Picture Card™) 12,000cycles (Memory Stick™)

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	0	Tray	SCDE1C0200	1
	Reverse mount			SCDE2B0100	2

Dimensions

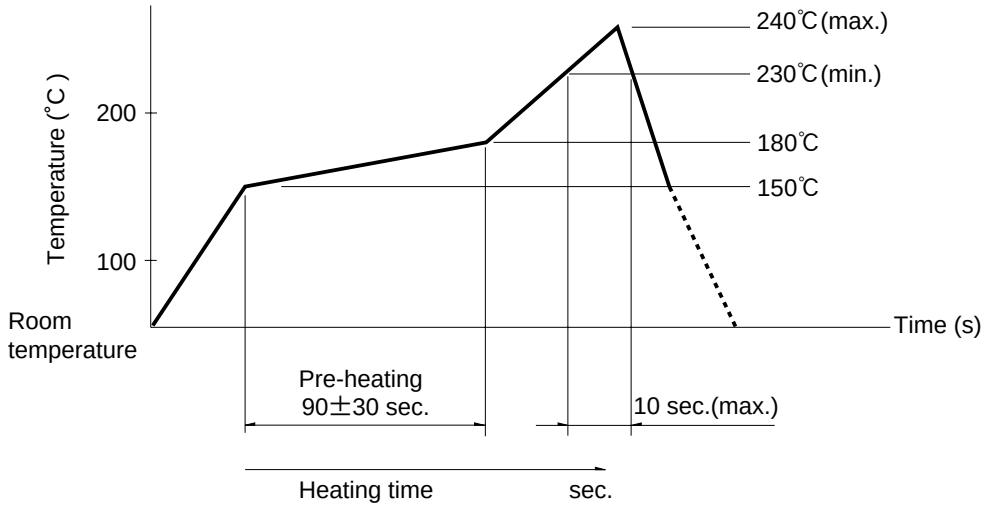
Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1		
2		

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with intrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. This product has been designed and manufactured for use in ordinary electronic equipment, such as AV equipment, electric home appliances, office machines and communication equipment. In case of using the products for highly sensitive applications such as medical, aviation, aerospace and security, the set makers shall require to include measures necessary to meet product safety requirements of such specific applications. Such measure may include additional protection circuits and redundant circuits, for example.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.